PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6104263

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SA XIAO	05/05/2020
TOM SCHNEIDER	05/05/2020
PING WAH WONG	05/05/2020

RECEIVING PARTY DATA

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION	
Street Address:	ress: 4-14-1 ASAHI-CHO	
Internal Address:	ATSUGI-SHI	
City:	KANAGAWA	
State/Country:	JAPAN	
Postal Code:	243-0014	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16868387

CORRESPONDENCE DATA

Fax Number: (303)863-0223

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 303-863-9700

Email: sony@sheridanross.com
Correspondent Name: SHERIDAN ROSS P.C.
Address Line 1: 1560 BROADWAY

Address Line 2: SUITE 1200

Address Line 4: DENVER, COLORADO 80202-5141

ATTORNEY DOCKET NUMBER: 6810USA-19 (KRC)	
NAME OF SUBMITTER:	KRISTEN R. COKAS
SIGNATURE:	/Kristen R. Cokas/
DATE SIGNED:	05/13/2020

Total Attachments: 3

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PATENT 506057549 REEL: 052649 FRAME: 0133

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PATENT REEL: 052649 FRAME: 0134

Attorney Docket No.: 6810USA-19 Sony Ref. No.: SP35715101

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	I IMACTING DEVICES AND DECOMPONE PODE FIGURE FERENCE	
As the below	named inventor, I hereby declare that:	
This declaration is directed to:	X The etteched amplication or	
•	United States application or PCT international application number filed on	
The above-ide	entified application was made or authorized to be made by me.	
WHEREAS,	I am the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at sahi-cho, Atsugi-shi, Kanagawa, Japan 243-0014 (hereinafter referred to as ASSIGNEE), is desirous of	
acquiring all i	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;	
of which are h representative to any and all all priority ri Convention R adheres, and t United States	EFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal es, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and I Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters ASSIGNEE, as the assignee of the whole right, title and interest thereto;	
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
	owledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of a five (5) years, or both.	
LEGAL NAM	1E OF INVENTOR	
Inventor:	Sa Xiao Date: 5/5/2020	
Signature:	YARAD So.	

Attorney Docket No.: 6810USA-19 Sony Ref. No.: SP35715101

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	IMAGING DEVICES AND DECODING METHODS THEREOF	
As the below	named inventor, I hereby declare that:	
This declaration is directed to: The attached application, or		
	United States application or PCT international application number filed on	
United States	application or PCT international application number	
	SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at	
	sahi-cho, Atsugi-shi, Kanagawa, Japan 243-0014 (hereinafter referred to as ASSIGNEE), is desirous of	
acquiring all i legal protection	nterest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;	
of which are h representative to any and all all priority ri Convention R adheres, and t United States	EFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency ereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal so the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and ghts and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American elating to Patents. Designs and Industrial Models, and any other international agreements to which the United States of America o any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters ASSIGNEE, as the assignee of the whole right, title and interest thereto:	
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense:		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAM	E OF INVENTOR	
Inventor:	Tom Schneider Date: May 5, 2020	
Signature:	Com & Brilled	

PATENT REEL: 052649 FRAME: 0136

Attorney Docket No.: 6810USA-19 Sony Ref. No.: SP35715101

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention IMAGING DEVICES AND DECODING METHODS THEREOF		
As the below named inventor, I hereby declare that:		
This declaration is directed to: The attached application, or		
United States application or PCT international application number filed on		
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at		
4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan 243-0014 (hereinafter referred to as ASSIGNEE), is desirous of		
acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;		
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;		
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF INVENTOR		
Inventor: Ping Wah Wong Date: J-J-2020		
Signature: Py who Wy		

PATENT REEL: 052649 FRAME: 0137

RECORDED: 05/13/2020